AEM Testing Innovation


# High-throughput Automated Burn-in with Intelligent Thermal Control

# AMPS-BI

Our AMPS high-parallel test platform now features **a high-power, high-throughput automated burn-in capability – AMPS-BI.** Targeting advanced high-power semiconductor devices, such as AI processors and high-performance computing units, the AMPS-BI system efficiently performs accelerated high voltage stress testing through the use of its patented advanced multi-zone intelligent thermal control and power management capabilities.

**AMPS-BI** is a fully automated operation with high parallelism and a scalable solution that reduces test times and enhances overall test coverage, delivering a significant cost-of-test advantage for our customers.

## Features

- Fully automated modular system - Capable of simultaneous high voltage stress testing of hundreds of devices in parallel
- Patented Multi-zone Intelligent Thermal Control (ITC). Scalable to >2KW per device, with precision control for thermal stability during test
- Application-specific test instruments - Optimized for customer requirements to ensure optimal yield
- Individual device test control and instrumentation allow for asynchronous operation, pattern changing on the fly, and high system utilization
- Support for device-specific change kits and consumables, including burn-in boards and sockets
- Support for advanced package formats, scalable beyond 100mm x 100mm package sizes
- Upgradable for System Level Test, tri-temperature, and higher throughput
- Fully supports JEDEC-based I/O with full Factory 4.0 automation support

## Capabilities

- >1,000A current per device
- Voltage ranges from 0.5V to 2V high current, 0.4V to 4V low current
- 48 digital channels at 100MHz per device (384 per test unit)
- 20 dedicated GPIO per device (160 per test unit)
- Per pin PMU
- 4*400MHz clocks per device (32 per test unit)
- Other power and channel configurations available upon request

## Talk to us today

globalsales@aem.com.sg

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